

# Wafer Mount

## NDS 212/208

- Suitable for 6", 8" and 12" wafer frames
- Compact desktop design
- Unsophisticated design, easy operation
- Reliable quality



### Specification

Items	Unit	NDS 212	NDS 208
Workpiece Size		12 inch	8 inch
Rated voltage		AC 200V	AC 200V
Frequency	Hz	50/60	50/60
Power	W	≤700	≤700
Air pressure	Mpa	0.5~0.7	0.5~0.7
Machine weight	kg	60	60
Machine dimensions	mm	1030x600x465	1030x600x465
Types of tape		Blue tape / White tape / UV tape	Blue tape / White tape / UV tape
Thickness of tape	mm	0.05~0.2	0.05~0.2
Temperature of stage	°C	0~70	0~70
Functions of tape mount		Manual	Manual
Functions of tape cut		Rotation by manual	Rotation by manual
Grounding resistance		below 4Ω	below 4Ω

\*Specifications are subject to change without notice

Roller hardness can reach 30 degrees and bubble-free while tape mounting.

Wafer positioning accuracy : deviation with  $\pm 1$ mm .

Avoid damage to products by adjusting the height according to the thickness of products.

Equipped with tape retrieve system and suitable for double layer tape.

Range of heater : room temperature ~ 70 °C ,

Adjustable and accuracy in temperature control :  $\pm 2$  °C

Avoid damage to wafer while mounting process by Teflon coating on the stage.

Stage can be designed to suit for different applications.

Throughput : more than 60 wafer/h.

ECD system is option.